

MOSFET - Power, Single N-Channel, SUPERFET®, EASY, PQFN88-4L

600 V, 80 mΩ, 40 A **NTMT080N60S5**

Description

SUPERFET V MOSFET Easy Drive series combines excellent switching performance without sacrificing ease of use and EMI issues for both hard and soft switching topologies. The Power88 package which is an ultraslim SMD package offers excellent switching performance by providing kelvin source configuration and lower parasitic source inductance.

Features

- Typ. $R_{DS(on)} = 64 \text{ m}\Omega$
- 100% Avalanche Tested
- Pb-Free, Halogen Free / BFR Free and are RoHS Compliant

Applications

- Telecom / Server Power Supplies
- EV Charger / UPS / Solar / Industrial Power Supplies

ABSOLUTE MAXIMUM RATINGS (T_J = 25°C, Unless otherwise noted)

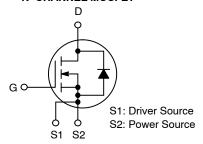
Parameter		Symbol	Value	Unit
Drain-to-Source Voltage		V _{DSS}	600	V
Gate-to-Source Voltage	DC	V _{GS}	±30	V
	AC (f > 1 Hz)		±30	
Continuous Drain Current	T _C = 25°C	I _D	40	Α
	T _C = 100°C		25	
Power Dissipation	T _C = 25°C	P_{D}	212	W
Pulsed Drain Current (Note 1)	T _C = 25°C	I _{DM}	116	Α
Pulsed Source Current (Body Diode) (Note 1)		I _{SM}	116	Α
Operating Junction and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C
Source Current (Body Diode)		I _S	40	Α
Single Pulse Avalanche Energy	$I_L = 5.8 A$ $R_G = 25 \Omega$	E _{AS}	287	mJ
Avalanche Current		I _{AS}	5.8	Α
Repetitive Avalanche Energy (Note 1)		E _{AR}	2.12	mJ
MOSFET dv/dt		dv/dt	120	V/ns
Peak Diode Recovery dv/dt (Note 2)			50	
Lead Temperature for Soldering Purposes (1/8" from case for 10 seconds)		T _L	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Repetitive rating: pulse-width limited by maximum junction temperature.
- 2. $I_{SD} \le 16.5 \text{ A}$, $di/dt \le 200 \text{ A/s}$, $V_{DD} \le 400 \text{ V}$, starting $T_{J} = 25^{\circ}\text{C}$.

V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
600 V	80 m Ω @ V _{GS} = 10 V	40 A

N-CHANNEL MOSFET





TDFN4 8x8 2P CASE 520AB

MARKING DIAGRAM

NTMT080 N60S5 **AWLYWW**

NTMT080N60S5 = Specific Device Code = Assembly Location WL = Wafer Lot = Year WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping [†]
NTMT080N60S5	TDFN4	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

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^{*}Drain current limited by maximum junction temperature.

THERMAL CHARACTERISTICS

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	0.59	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{ heta JA}$	45	

ELECTRICAL CHARACTERISTICS (T_{.1} = 25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
OFF CHARACTERISTICS					-	
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V, } I_D = 1 \text{ mA, } T_J = 25^{\circ}\text{C}$	600	-	_	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	ΔV _{(BR)DSS} / ΔT _J	I _D = 10 mA, Referenced to 25°C	-	630	-	mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V, V _{DS} = 600 V, T _J = 25°C	-	-	2	μΑ
Gate-to-Source Leakage Current	I _{GSS}	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	±100	nA
ON CHARACTERISTICS						
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V, I _D = 16.5 A, T _J = 25°C	-	64	80	mΩ
Gate Threshold Voltage	V _{GS(th)}	$V_{GS} = V_{DS}, I_D = 3.4 \text{ mA}, T_J = 25^{\circ}\text{C}$	2.4	-	4	V
Forward Trans-conductance	9FS	V _{DS} = 20 V, I _D = 16.5 A	-	28.8	-	S
CHARGES, CAPACITANCES & GATE	RESISTANCE				-	
Input Capacitance	C _{ISS}	$V_{DS} = 400 \text{ V}, V_{GS} = 0 \text{ V}, f = 250 \text{ kHz}$	-	3029	_	pF
Output Capacitance	C _{OSS}		-	47.1	-	1
Time Related Output Capacitance	C _{OSS(tr.)}	I_D = Constant, V_{DS} = 0 V to 400 V, V_{GS} = 0 V	-	746	6 –	
Energy Related Output Capacitance	C _{OSS(er.)}	V _{DS} = 0 V to 400 V, V _{GS} = 0 V	-	83.8	-	
Total Gate Charge	Q _{G(tot)}	V _{DD} = 400 V, I _D = 16.5 A, V _{GS} = 10 V	-	56.2	_	nC
Gate-to-Source Charge	Q_{GS}		-	14.8	-	
Gate-to-Drain Charge	Q_{GD}		-	16.3	_	
Gate Resistance	R_{G}	f = 1 MHz	-	5.66	_	Ω
SWITCHING CHARACTERISTICS					-	
Turn-On Delay Time	t _{d(on)}	$V_{GS} = 0/10 \text{ V}, V_{DD} = 400 \text{ V},$	-	29.4	_	ns
Rise Time	t _r	$I_D = 16.5 \text{ A}, R_G = 4.7 \Omega$	-	11.4	-	
Turn-Off Delay Time	t _{d(off)}		-	88.2	-	
Fall Time	t _f	1	-	3.62	_	
SOURCE-TO-DRAIN DIODE CHARAC	TERISTICS			-	•	-
Forward Diode Voltage	V_{SD}	V _{GS} = 0 V, I _{SD} = 16.5 A, T _J = 25°C	-	_	1.2	V
Reverse Recovery Time	t _{RR}	V _{GS} = 0 V, I _{SD} = 16.5 A,	-	338	-	ns
Reverse Recovery Charge	Q _{RR}	dI/dt = 100 A/μs, V _{DD} = 400 V	_	5167	_	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

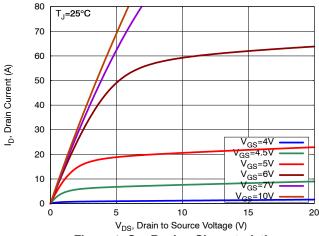


Figure 1. On-Region Characteristics

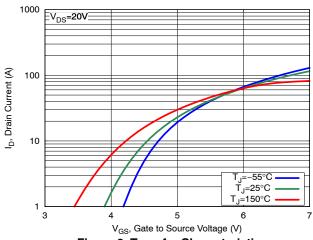


Figure 2. Transfer Characteristics

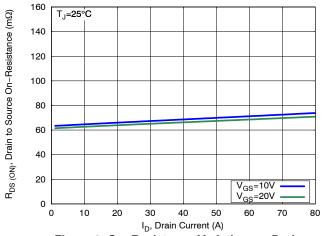


Figure 3. On–Resistance Variation vs. Drain Current and Gate Voltage

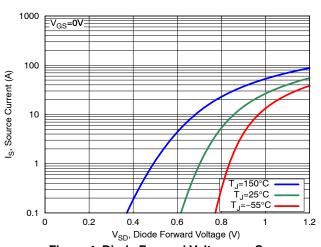


Figure 4. Diode Forward Voltage vs. Source
Current

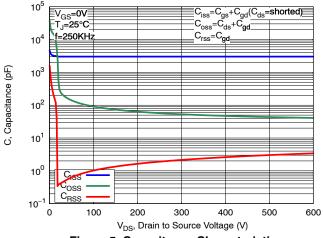


Figure 5. Capacitance Characteristics

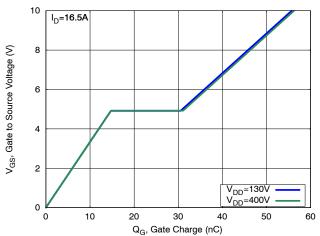


Figure 6. Gate Charge Characteristics

TYPICAL CHARACTERISTICS

ID, Drain Current (A)

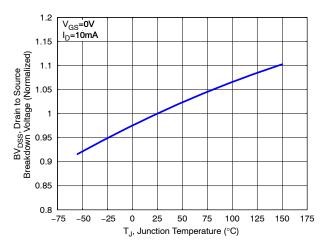


Figure 8. Breakdown Voltage Variation vs. Temperature

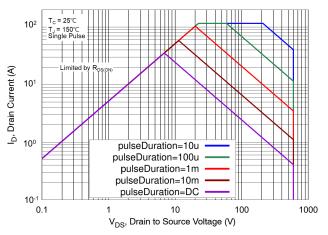


Figure 9. Maximum Safe Operating Area

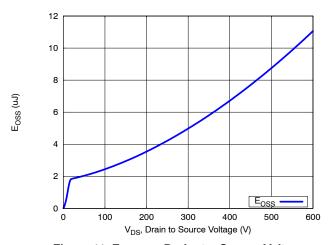


Figure 11. Eoss vs. Drain-to-Source Voltage

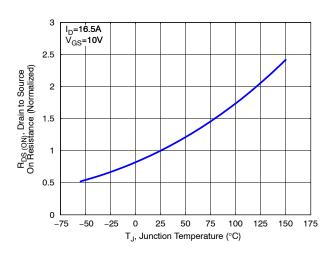


Figure 7. On–Resistance Variation vs.
Temperature

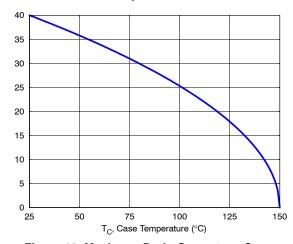


Figure 10. Maximum Drain Current vs. Case Temperature

TYPICAL CHARACTERISTICS

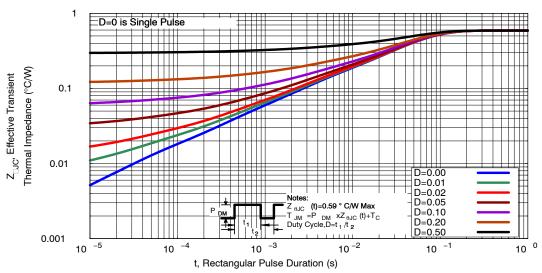
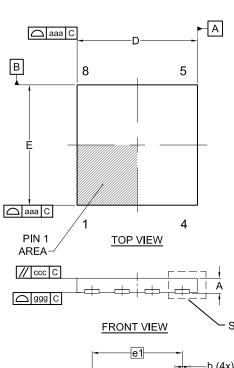


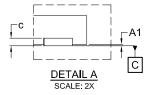
Figure 12. Transient Thermal Impedance

PACKAGE DIMENSIONS

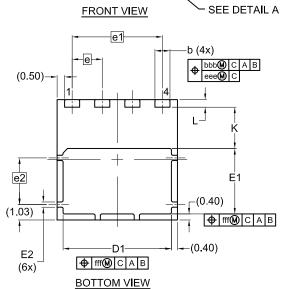
TDFN4 8x8, 2P CASE 520AB ISSUE O

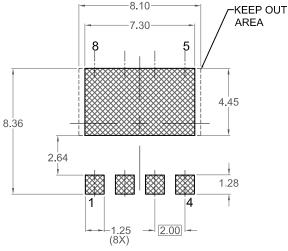


- NOTES: UNLESS OTHERWISE SPECIFIED
- A) DOES NOT FULLY CONFORM TO JEDEC REGISTRATION MO-220.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
 C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D) IT IS RECOMMENDED TO HAVE NO TRACES OR VIAS WITHIN THE KEEP OUT AREA.



MILLIMETEDS			
MIN.	NOM.	MAX.	
0.90	1.00	1.10	
0.00		0.05	
0.90	1.00	1.10	
0.10	0.20	0.30	
7.90	8.00	8.10	
7.10	7.20	7.30	
7.90	8.00	8.10	
4.25	4.35	4.45	
0.15	0.25	0.35	
2.00 BSC			
6.00 BSC			
3.10 BSC			
(2.75)			
0.40	0.50	0.60	
0.10			
0.10			
0.05			
0.05			
0.10			
0.15			
	MIN. 0.90 0.00 0.90 0.10 7.90 7.10 7.90 4.25 0.15	0.90 1.00 0.00 0.90 1.00 0.10 0.20 7.90 8.00 7.10 7.20 7.90 8.00 4.25 4.35 0.15 0.25 2.00 BS 6.00 BS 3.10 BS (2.75) 0.40 0.50 0.10 0.05 0.05	





RECOMMENDED LAND PATTERN

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